

# SOT2147-1

VFPGA512, very thin fine-pitch ball grid array package, 512 terminals, 0.4 mm pitch, 9.4 mm x 9.4 mm x 0.811 mm body

6 February 2023

Package information



## 1 Package summary

|                                       |  |
|---------------------------------------|--|
| <b>Terminal position code</b>         | B (bottom)                                   |
| <b>Package type descriptive code</b>  | VFPGA512                                     |
| <b>Package style descriptive code</b> | VFPGA (very thin fine-pitch ball grid array) |
| <b>Mounting method type</b>           | S (surface mount)                            |
| <b>Issue date</b>                     | 15-06-2021                                   |
| <b>Manufacturer package code</b>      | 98ASA01806D                                  |

Table 1. Package summary

| Parameter                      | Min | Nom   | Max   | Unit |
|--------------------------------|-----|-------|-------|------|
| package length                 | 9.3 | 9.4   | 9.5   | mm   |
| package width                  | 9.3 | 9.4   | 9.5   | mm   |
| package height                 | -   | 0.811 | 0.911 | mm   |
| nominal pitch                  | -   | 0.4   | -     | mm   |
| actual quantity of termination | -   | 512   | -     |      |



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2 Package outline

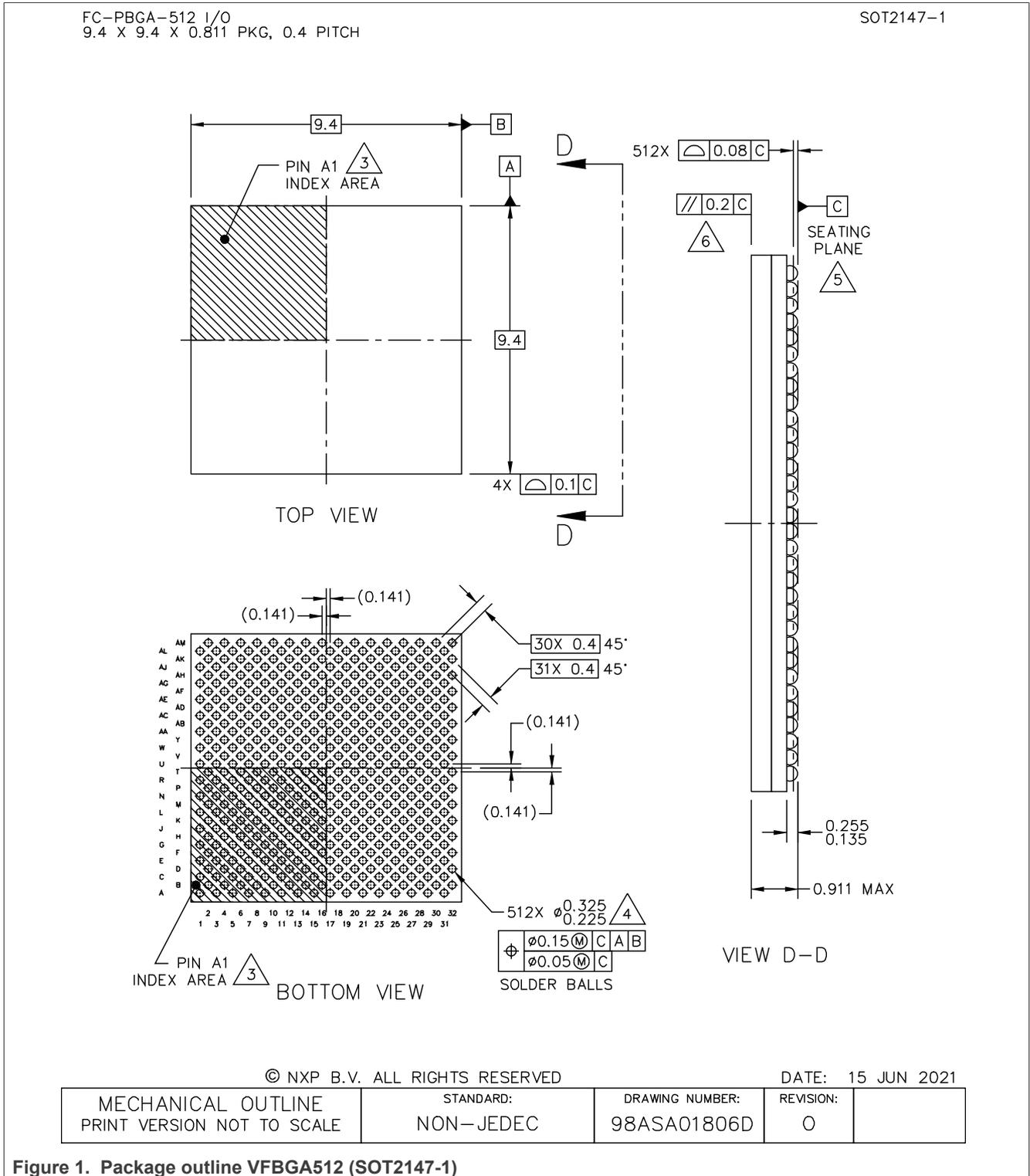
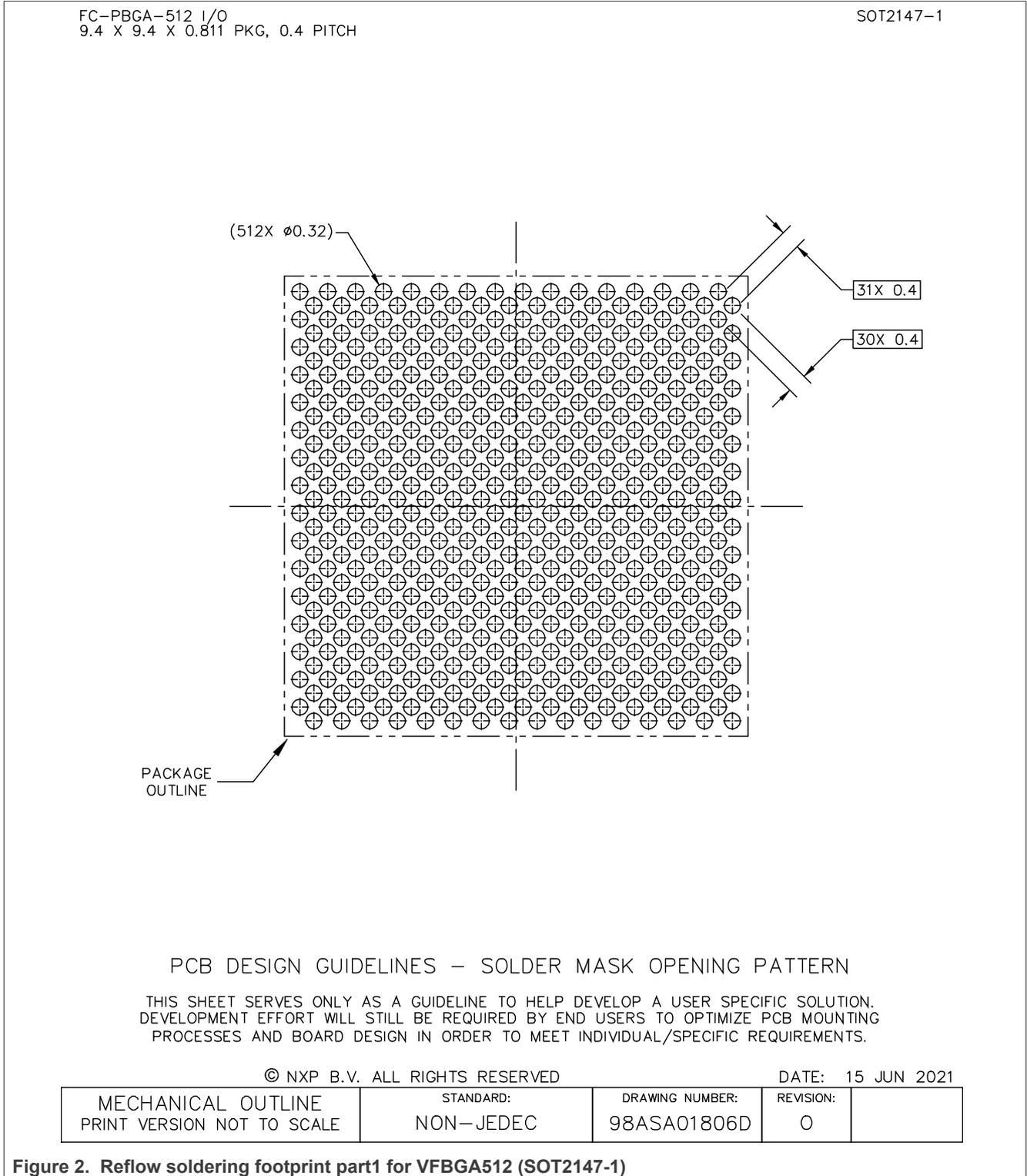


Figure 1. Package outline VFBGA512 (SOT2147-1)

VFBGA512, very thin fine-pitch ball grid array package, 512 terminals, 0.4 mm pitch, 9.4 mm x 9.4 mm x 0.811 mm body

3 Soldering



## 4 Legal information

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